Company : Qualcomm
Company
Name : Qualcomm India Pvt Ltd

Nature Of Business : Designation

SemiConductor

Engineering - Software

Tentative Job Location :

**Description:** 

Hyderabad / Bangalore / Chennai / Noida

Job Area: Engineering - Software

Job Location: Hyderabad / Bangalore / Chennai / Noida

We know our employees' ideas change the world. For more than three decades, we've been a global leader in mobile technology, continually pushing the boundaries of what's possible.

Working with customers across industries — from automotive to health care, from smart cities to robotics— we continue to accelerate innovation and unlock new possibilities in a time where everything is connected. By joining the Qualcomm family, you too can bring the future forward faster.

As a software engineer, you will design, develop Software for Qualcomm's mobile chipsets which are based on cutting edge technology.. Qualcomm is looking for energetic, creative and self-driven engineer to work in

➢ Multimedia Technologies such as Audio and Video codecs, Image Processing, ➢ Wireless Modem Technologies, such as 4G, WiFi, Bluetooth, Self-Organizing Networks. ➢ Platform Level SW, such as, Linux, Android, Windows, Board Support Packages. ➢ IOT Technologies, for Connected Cameras, Smart Assistants, Drones, Virtual Reality,

Augmented Reality.

Campus Grads will be working on following areas:

- Development of real-time embedded software and device drivers
- Mobile SW development for Windows Mobile, Android or Linux
  - Good understanding of OS concepts, Data structures, etc
    - C/C++ and object oriented design
  - Wireless network standards such as CDMA/GSM/UMTS/LTE
    - Linux/UNIX, Linux Drivers, Linux Kernel Development
      - Protocols such TCP/UDP/IP/SIP/RTP etc
  - Multimedia technologies including Audio, Video, Imaging
    - Excellent analytical and problem solving skills
      - Ability to collaborate and work in teams.
    - Good verbal and written communication skill

### Opportunities include:

- SW development for Android, Window Mobile based Embedded Platforms
  - Multimedia software stack, firmware and driver Development
- Wireless Modem and connectivity Software and Firmware Development
  - Communication protocol stack Software Development
    - Kernel, BSP and Device Driver Development
      - Application SW and UI development.
  - SW Architecture for embedded devices based on Android, Windows.
  - Design and development based on Object oriented programming.

## Education:

Masters, Bachelors: Computer Science Engineering, Communication Engineering, ECE,

Program	AE BSBE	CE CHE	CSE	EE ES M	IE MSI	E PHY	CHM	I MTH	ECC	) DES	IME	CGS	HSS	EEM	MSP	NET	PSE	Stats
BT	No No	No No	Yes	Yes N	o No													
BS				No		No	No	No	No									
MT	No No	No No	Yes	Yes No N	o No						No			No	No	No	Yes	

	DoubleMajor	No No	No No	Yes	Yes ·	No	No	No	No	No	No									
	dual	No No	No No	Yes	Yes	No No	No	No	No	No	No									
Eligibilty:	dualB	No No	No No	Yes	Yes ·	No	No	No	No	No	No		No			No		No	Yes	
	dualC	No No	No No	Yes	Yes	No No														
	Mdes											No								
	MBA												No							
	Phd	No No	No No	No	No :	No No	No	No												
	MSc							No	No	No										No
	MSR	No No	No No	Yes	Yes ·	No	No							No					Yes	

### Compensation For M.Tech Students(DD/ M.Tech/ MS by Research): Engineer

Component Amount Total Gross Pay INR 12.50 L Retirals (PF and Gratuity) INR 0.75 L Performance Bonus\* INR 0.70 L Joining Bonus INR 4.60 L Relocation Bonus (Paid within 60 days) INR 0.50 L

Restricted Stock Value Awards (Vesting in

INR 12.00 L (\$ 16000) 3 years )\*\*

\*Based on individual & Organization Performance || \*\*RSU -33% vesting every year

Additional Benefits: Relocation Assistance, Insurance, Transportation

\$1= INR 75

Cost to **Company:** 

Title: Associate Engineer | Degree: B.Tech

**NEW** 

Component Amount Total Gross Pay INR 11.50 L Retirals (PF and Gratuity) INR 0.69 L Performance Bonus\* INR 0.70 L Joining Bonus INR 4.35 L INR 0.50 L Relocation Bonus ( Paid within 60 days )

RSU - Restricted Stock Value Awards INR 7.50 L (\$10000) (Vesting in 3 years)\*\*

\*Based on Individual & Organization Performance || \*\*RSU -33% vesting every year

Additional Benefits: Relocation Assistance, Insurance, Transportation.

## \$1=INR 75

#### Compensation For M.Tech Students(DD/ M.Tech/ MS by Research): Engineer

Component **Amount** Total Gross Pay INR 12.50 L Retirals (PF and Gratuity) INR 0.75 L Performance Bonus\* INR 0.70 L Joining Bonus INR 4.60 L Relocation Bonus (Paid within 60 days) INR 0.50 L

Restricted Stock Value Awards (Vesting in INR 12.00 L (\$ 16000)

3 years )\*\*

\*Based on individual & Organization Performance || \*\*RSU -33% vesting every year

Additional Benefits: Relocation Assistance, Insurance, Transportation

\$1= INR 75

**Package** Details:

Title: Associate Engineer | Degree: B.Tech

**NEW** 

Component Amount Total Gross Pay INR 11.50 L Retirals (PF and Gratuity) INR 0.69 L Performance Bonus\* INR 0.70 L Joining Bonus INR 4.35 L Relocation Bonus ( Paid within 60 days ) INR 0.50 L

RSU - Restricted Stock Value Awards

Number of Techincal

Interview Rounds: HR

Interview: HR Interview

Duration: Additional Information:

# \*Based on Individual & Organization Performance || \*\*RSU -33% vesting every year Additional Benefits: Relocation Assistance, Insurance, Transportation.

0

True

N/A

	Additional Benefits: Relocation Assistance
	\$1=INR 75
Bond:	False
CPI CutOff:	0.0
Medical	
Requirments	NA
:	
Resume	True
Shortlist :	1140
Resume	
Shortlist	N/A
Criteria:	
Aptitude	True
Test:	
Aptitude Test	N/A
Duration:	N/A
Group	
Discussion:	False
Technical	
Test:	True
Technical	
Test	N/A
<b>Duration:</b>	
Technical	True
Interview:	True
Technical	
Interview	N/A
Duration:	